

Fuseholder Open Design, 5 x 20 mm, SMD, var. Covers, IEC 60335-1



250 VAC · 4 W / 10 A (VDE) · 500 VAC/DC · 10 A (UL/CSA)

**Description**

- For appliances in unattended use
- Glow wire tests acc. to IEC 60695-2-12 and -13
- Low profile fuse block with insulation walls

Standards

- IEC 60127-6
- UL 4248-1 / UL 512
- CSA C22.2 no. 39

Approvals

- VDE Certificate Number: 40001042
- UL File Number: E39328
- CSA File Number: 38456

Applications

- Industrial electronic
- Household appliances

References

[Packaging Details](#)

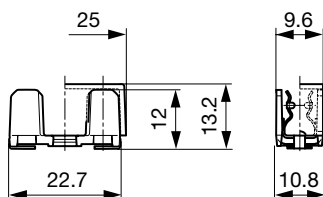
Weblinks

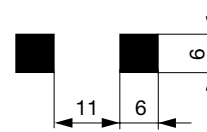
[pdf-datasheet](#), [html-datasheet](#), [General Product Information](#), [Approvals](#), [CE declaration of conformity](#), [RoHS](#), [CHINA-RoHS](#), [e-Shop](#), [SCHURTER-Stock-Check](#), [Distributor-Stock-Check](#), [Accessories](#), [Detailed request for product](#)

Technical Data

Fuse-Link	5 x 20 mm
Mounting	PCB
Terminal	Solder SMT
Rated Voltage	250 VAC (VDE), 500 VAC/DC (UL/CSA)
Rated Current	10 A (VDE), 10 A (UL/CSA)
Rated Power Acceptance IEC	4 W / 10 A @ Ta 23 °C 2.5 W / 10 A with transparent cover, see derating curves
Degree of Protection	IP 00 / IP 20
Protection Class	Suitable for appliances with protection class I or II acc. to IEC 61140
Admissible Ambient Air Temp.	-40 °C to 85 °C
Climatic Category	40/085/21 acc. to IEC 60068-1
Material: Socket	see variants
Material: Cover	Thermoplastic UL 94V-0
Material: Terminals	Tin-Plated Copper Alloy
Unit Weight (Socket/Cap)	1.7 g
Storage Conditions	0 °C to 60 °C, max. 70% r.h.
Product Marking	 Type, Dielectric strength, Power Acc./Current Rating, Approvals

Soldering Methods	Reflow (see variants)
Solderability	245 °C / 3 sec acc. to IEC 60068-2-58, Test Td
Resistance to Soldering Heat	240 - 260 °C / 20 - 40 sec acc. to IPC/JEDEC J-STD-020C
Contact Resistance	< 5 mΩ at 20 mV
Dielectric Strength	> 3 kV (50 Hz; 1 min)
Impulse Withstand Voltage	> 4 kV between L-N
Insulation Resistance	> 10 MΩ between L-N (500 VDC; 1 min)
Overvoltage Category	I - III acc. to IEC 60664-1
Pollution Degree	1 - 3 acc. to IEC 60664-1
Resistance to Vibration	acc. to IEC 60068-2-6, test Fc

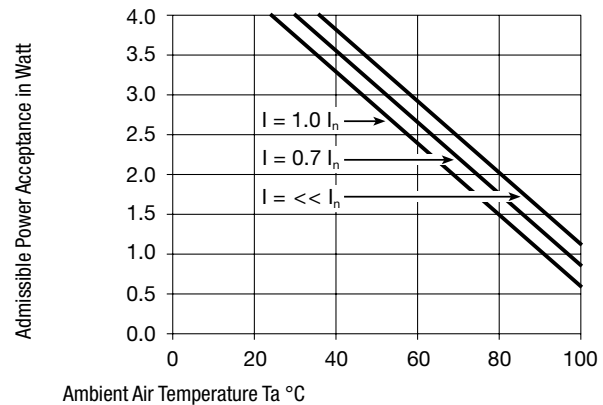
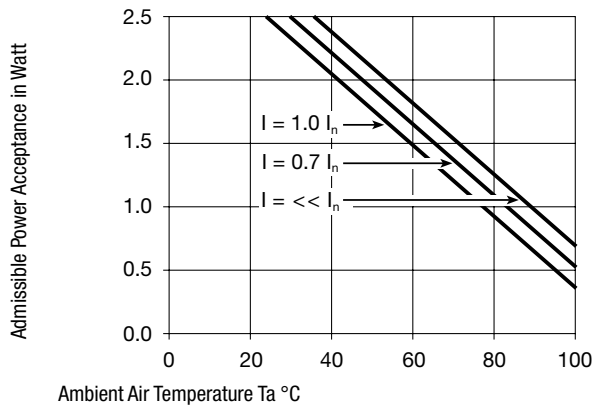
Dimensions



Soldering pads

Derating Curves

With Transparent Cover



Variants

Holder	Material	Material: Terminals	Reflow Condition	Packaging	Order Number
●	Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020C, Tp=240 +/-5 °C, tp = 20-40 s	Bulk 128 x 91 x 60 mm (100 pcs.)	0031.8221
●	Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020C, Tp=240 +/-5 °C, tp = 20-40 s	Blister Tape 38 cm Reel (400 pcs.)	0031.8225
●	Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020C, Tp=240 +/-5 °C, tp = 20-40 s	Blister Tray 266 x 173 mm (500 pcs.)	0031.8222
●	Spec. Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020C, Tp=260 +/-5 °C, tp = 20-40 s	Bulk 128 x 91 x 60 mm (100 pcs.)	0031.8263
●	Spec. Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020C, Tp=260 +/-5 °C, tp = 20-40 s	Blister Tape 38 cm Reel (400 pcs.)	0031.8265
●	Spec. Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020C, Tp=260 +/-5 °C, tp = 20-40 s	Blister Tray 266 x 173 mm (500 pcs.)	0031.8264
●	Spec. Thermoplastic	Gold-Plated Copper Alloy	acc. to JEDEC J-STD-020C, Tp=260 +/-5 °C, tp = 20-40 s	Bulk 128 x 91 x 60 mm (100 pcs.)	0031.8273
●	Spec. Thermoplastic	Gold-Plated Copper Alloy	acc. to JEDEC J-STD-020C, Tp=260 +/-5 °C, tp = 20-40 s	Blister Tape 38 cm Reel (400 pcs.)	0031.8275
●	Spec. Thermoplastic	Gold-Plated Copper Alloy	acc. to JEDEC J-STD-020C, Tp=260 +/-5 °C, tp = 20-40 s	Blister Tray 266 x 173 mm (500 pcs.)	0031.8274

Spec. thermoplastic meets the requirements acc. to IEC 60335-1 Ed. 4.0 for appliances in unattended use (clause 30.2.3). This standard includes the enhanced requirements of glow wire tests acc. to IEC 60695-2-12 and -13.

Fuseholders with gold-plated terminals are more heat resistant than fuseholders with tin-plated terminals.

If soldering problems occur with the thermoplastic version, it is recommended to use the spec. thermoplastic with tin-plated and gold-plated terminals.

Packaging Unit

see variants

Accessories

Description



Covers for OGN, OGN-SMD

Cover for Holder OGN, OGN-SMD

Adapter to OGN, OGN-SMD

Fuse Carriage with Handle for OGN, OGN-SMD

Order numbers for pre-assembled OGN-SMD, blister tape packaging with 400 pieces per reel

Rated current In	FTT 5x20 with reflow cover 0853.0571	FTT 5x20 no cover	FST 5x20 with reflow cover 0853.0571	FST 5x20 no cover	FSF 5x20 with reflow cover 0853.0571	FSF 5x20 no cover	SPT 5x20 with reflow cover 0853.0571	SPT 5x20 no cover
50 mA			0031.8304	0031.8354				
63 mA	0031.8501	0031.8551	0031.8305	0031.8355				
80 mA	0031.8502	0031.8552	0031.8306	0031.8356				
100 mA	0031.8503	0031.8553	0031.8307	0031.8357				
125 mA	0031.8504	0031.8554	0031.8308	0031.8358				
160 mA	0031.8505	0031.8555	0031.8309	0031.8359				
200 mA	0031.8506	0031.8556	0031.8310	0031.8360				
250 mA	0031.8507	0031.8557	0031.8311	0031.8361				
315 mA	0031.8508	0031.8558	0031.8312	0031.8362				
400 mA	0031.8509	0031.8559	0031.8313	0031.8363				
500 mA	0031.8510	0031.8560	0031.8314	0031.8364	0031.8413	0031.8463		
630 mA	0031.8511	0031.8561	0031.8315	0031.8365	0031.8414	0031.8464		
800 mA	0031.8512	0031.8562	0031.8316	0031.8366	0031.8415	0031.8465		
1 A	0031.8513	0031.8563	0031.8317	0031.8367	0031.8416	0031.8466	0031.8993	0031.9007
1,25 A	0031.8514	0031.8564	0031.8318	0031.8368	0031.8417	0031.8467	0031.8994	0031.9008
1,6 A	0031.8515	0031.8565	0031.8319	0031.8369	0031.8418	0031.8468	0031.8995	0031.9009
2A	0031.8516	0031.8566	0031.8320	0031.8370	0031.8419	0031.8469	0031.8996	0031.9010
2,5 A	0031.8517	0031.8567	0031.8321	0031.8371	0031.8420	0031.8470	0031.8997	0031.9011
3,15 A	0031.8518	0031.8568	0031.8322	0031.8372	0031.8421	0031.8471	0031.8998	0031.9012
4 A	0031.8519	0031.8569	0031.8323	0031.8373	0031.8422	0031.8472	0031.8999	0031.9013
5 A			0031.8324	0031.8374	0031.8423	0031.8473	0031.9000	0031.9014
6,3 A			0031.8325	0031.8375	0031.8424	0031.8474	0031.9001	0031.9015
8 A			0031.8326	0031.8376	0031.8425	0031.8475	0031.9002	0031.9016
10 A			0031.8327	0031.8377	0031.8426	0031.8476	0031.9003	0031.9017

All fuses in the pre-assembled OGN-SMD fuseholders are suitable for the reflow solder process.

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9